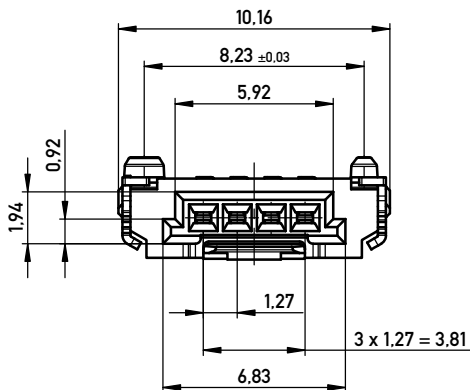
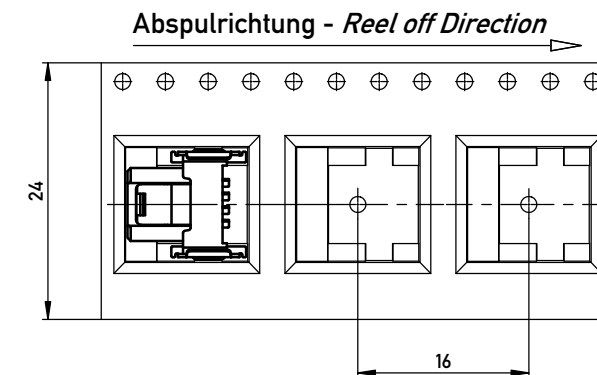
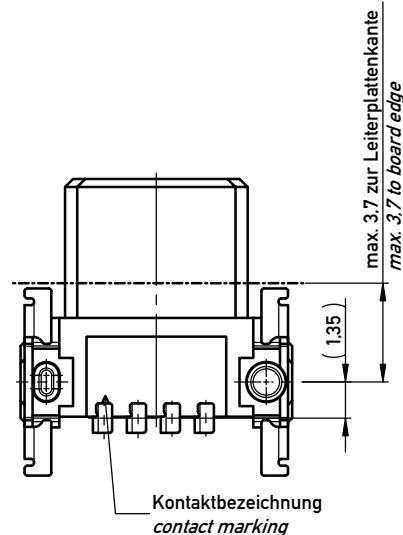
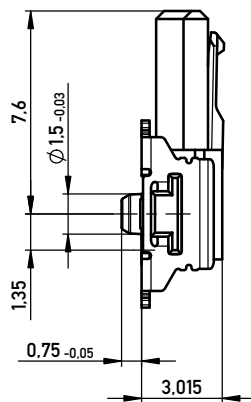
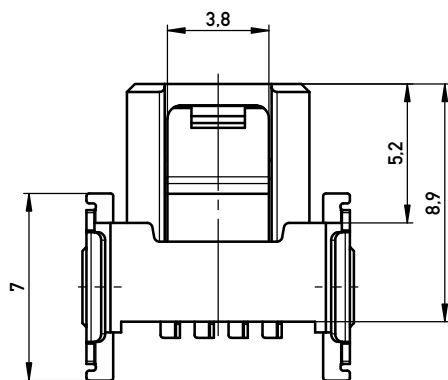
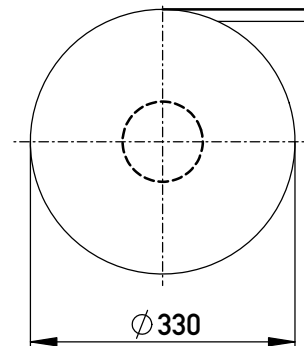
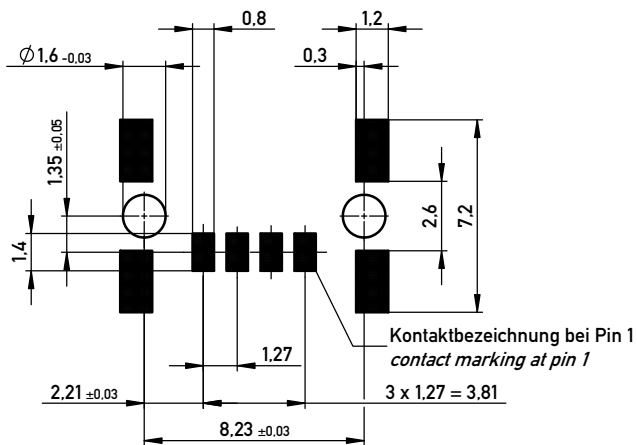


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 850 Stück
Packaging unit: 850 pcs



Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 μm
Terminal Area 4-6 μm tin plating

Koplanarität der Anschlüsse ≤ 0.1 mm
Coplanarity Area of Termination ≤ 0.1 mm

mit Verriegelung
with locking mechanism

Information: ohne Hilfsmittel lösbar without tool unlockable	Tolerances	 All Dimensions in mm	Scale	5:1
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b	15.07.2015		Class	SRCP
Index	Date			

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